Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	16
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	6.52 E-01	87.7	877000	58.48	584845
Thermosets	Epoxy Resin	Proprietary	3.72 E-02	5.0	50000	3.33	33343
Thermosets	Phenol Resin	Proprietary	3.72 E-02	5.0	50000	3.33	33343
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.49 E-02	2.0	20000	1.33	13337
Other inorganic materials	Carbon Black	1333-86-3	2.23 E-03	0.3	3000	0.20	2001
Subtotal			7.44 E-01	100	1000000	66.69	666870

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.33 E-01	97.57	975706	29.89	298919
Copper & its alloys	Iron	7439-89-6	7.79 E-03	2.28	22789	0.70	6982
Copper & its alloys	Zinc	7440-66-6	4.32 E-04	0.13	1263	0.04	387
Copper & its alloys	Phosphorus	7723-14-0	8.29 E-05	0.02	242	0.01	74
Subtotal			3.42 E-01	100.00	1000000	30.64	306362

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.70 E-04	100.0	1000000	0.09	870

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.83 E-02	100.0	1000000	1.64	16432

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.20 E-04	99.99	1000000	0.06	556

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.52 E-03	100.0	1000000	0.67	6741

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.86 E-03	80	800000	0.17	1671
Thermosets	Epoxy Resin	Proprietary	3.50 E-04	15	150000	0.03	313
Others	Curing agent & hardener	Proprietary	1.17 E-04	5	50000	0.01	104
Subtotal			2.33 E-03	100	1000000	0.21	2089

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	5.44 E-05	60.4	604000	0.005	49
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	2.52 E-05	28.0	280000	0.002	23
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	9.00 E-06	10.0	100000	0.001	8
Other organic materials	Ethylbenzene	100-41-4	9.00 E-07	1.0	10000	0.00008	1
Other organic materials	Xylene	1330-20-7	5.40 E-07	0.6	6000	0.00005	0.5
Subtotal			9.00 E-05	100.0	1000000	0.01	81

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.12 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	16
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	6.52 E-01	87.7	877000	58.49	584892
Thermosets	Epoxy Resin	Proprietary	3.72 E-02	5.0	50000	3.33	33346
Thermosets	Phenol Resin	Proprietary	3.72 E-02	5.0	50000	3.33	33346
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.49 E-02	2.0	20000	1.33	13338
Other inorganic materials	Carbon Black	1333-86-3	2.23 E-03	0.3	3000	0.20	2001
Subtotal			7.44 E-01	100	1000000	66.69	666924

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.33 E-01	97.57	975706	29.89	298943
Copper & its alloys	Iron	7439-89-6	7.79 E-03	2.28	22789	0.70	6982
Copper & its alloys	Zinc	7440-66-6	4.32 E-04	0.13	1263	0.04	387
Copper & its alloys	Phosphorus	7723-14-0	8.29 E-05	0.02	242	0.01	74
Subtotal			3.42 E-01	100.00	1000000	30.64	306387

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.70 E-04	100.0	1000000	0.09	870

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.56 E-02	85.0	850000	1.40	13968
Tin & its alloys	Lead	7439-92-1	2.75 E-03	15.0	150000	0.25	2465
Subtotal			1.83 E-02	100.0	1000000	1.64	16433

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.20 E-04	99.99	1000000	0.06	556

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.52 E-03	100.0	1000000	0.67	6742

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.71 E-03	73.40	734000	0.15	1533
Thermoset	Epoxy Resin	Proprietary	4.28 E-04	18.35	183500	0.04	383
Other inorganic materials	Metal oxide	Proprietary	6.41 E-05	2.75	27500	0.01	57
Others	Curing and hardening agent	Proprietary	6.41 E-05	2.75	27500	0.01	57
Other organic materials	Gamma Butyrolactone	96-48-0	6.41 E-05	2.75	27500	0.01	57
Subtotal			2.33 E-03	100.00	1000000	0.21	2089

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.12 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability t
any inaccuracy of such information.

ANALOG DEVICES

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